ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composit © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	Il rights reserved nations.	under both	This docum level parts, t	ent is a decla the declaration	aration on enco	of the substance ompasses all low	es within the ver level mat	manufactur erials for wh	er listed ite hich the ma	em. Note: anufacture	if the item is an a er has engineering	ssembly with lower responsibility.
1752-21.1					Form Type * Distribute	Form Type * Declaration Class * Distribute Class 6 - RoHS Yes/Not			o, Homogeneous Materials and Mfg Information						
Supplier Informa	ation														
Company name*			Company unique ID			Unique ID Authority					Response Date*				
onsemi												2025-05-13			
Contact Name			Title - Contact				Phone - Contact*					Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective I	Date V	Version Manufacturing Site		V	/eight*	UOM	Unit Type	
		NCID9400R2 High Speed Qu T&R		High Speed Quad T&R	d Channel Digital	nnel Digital Isolator 202		3		PBB		4	23.399	mg	Each
Manufacturing P	Proccess Information	1													
Terminal Plating / Grid Array Material			erminal Base Alloy J-STD-020 MSI		Rating	Peak Process Body Temperature		ire Max Time at Peak Tempera		Temperatu	re Num	ber of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Alloy				1		260		С	30		second	s 3			
Comments															
level 1 - maximum tir	me at peak temperature d	luring sol	dering is 10-3	0 seconds											
For more information	n regarding material com	position j	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
DBC	54.376	mg	Supplier	Silver (Ag)	7440-22-4		0.0816	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		38.7918	mg
			В	Nickel (Ni)	7440-02-0		0.1305	mg
			Supplier	Copper (Cu)	7440-50-8		15.3721	mg
Die	2.997	mg	Supplier	Silicon (Si)	7440-21-3		2.997	mg
Epoxy	0.036	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0032	mg
			Supplier	Proprietary	Proprietary Data		0.0002	mg
			Supplier	Bismaleimide	13676-54-5		0.0182	mg
			Supplier	PTFE	9002-84-0		0.0144	mg
Lead Frame	65.486	mg	Supplier	Silver (Ag)	7440-22-4		0.1965	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1244	mg
			Supplier	Iron (Fe)	7439-89-6		1.6961	mg
			Supplier	Copper (Cu)	7440-50-8		63.3773	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0917	mg
Mold Compound-Black	296.395	mg		Epoxy resin	proprietary data		17.7837	mg
			Supplier	Phenolic Resin	Proprietary Data		17.7837	mg
			Supplier	Carbon Black (C)	1333-86-4		1.482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		251.9357	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		7.4099	mg
lating	3.143	mg	Supplier	Tin (Sn)	7440-31-5		3.143	mg
Solder Paste	0.595	mg	Supplier	Silver (Ag)	7440-22-4		0.0149	mg
			А	Lead (Pb)	7439-92-1	7a	0.5504	mg
			Supplier	Tin (Sn)	7440-31-5		0.0298	mg
Wire Bond - Au	0.371	mg	Supplier	Gold (Au)	7440-57-5		0.371	mg